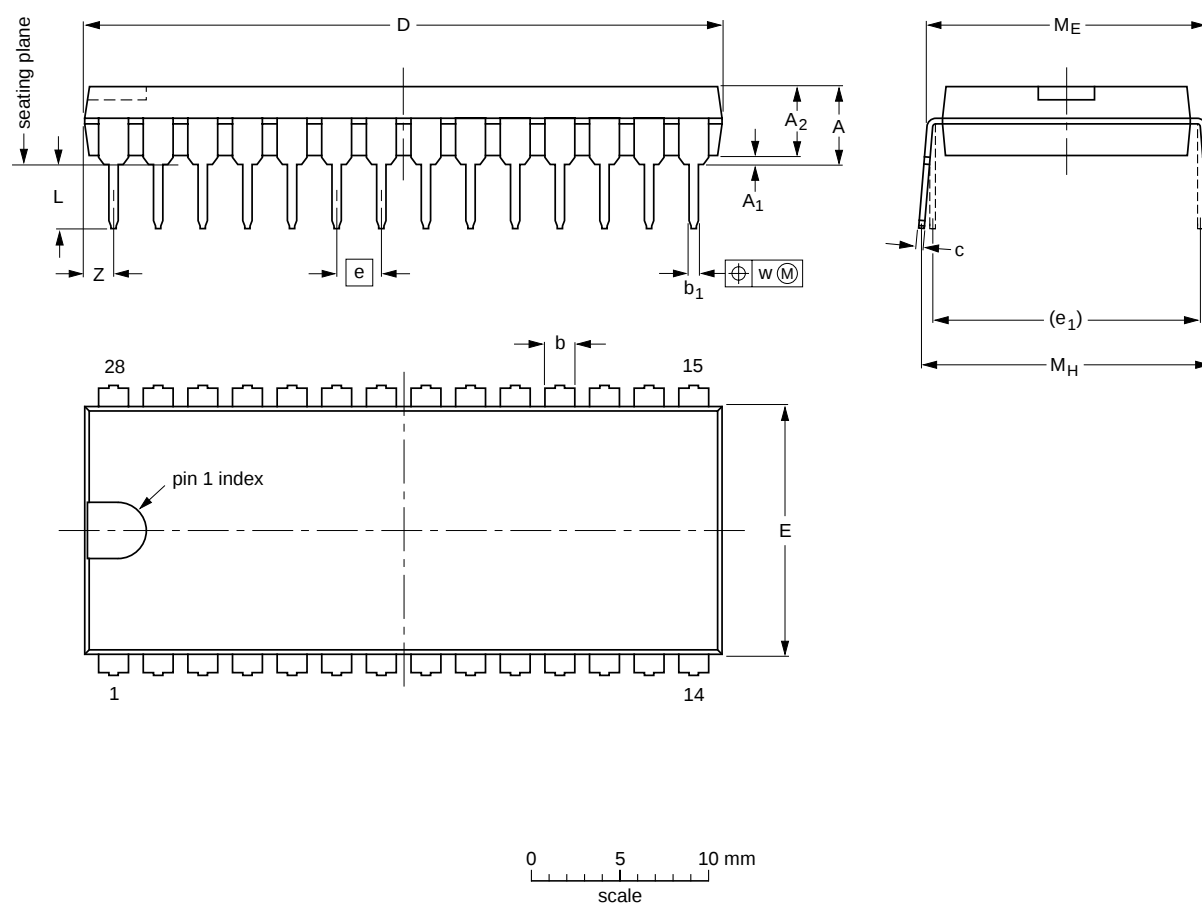


Philips Semiconductors

Package outline

DIP28: plastic dual in-line package; 28 leads (600 mil)

SOT117-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	5.1	0.51	4	1.7 1.3	0.53 0.38	0.32 0.23	36 35	14.1 13.7	2.54	15.24	3.9 3.4	15.80 15.24	17.15 15.90	0.25	1.7
inches	0.2	0.02	0.16	0.066 0.051	0.020 0.014	0.013 0.009	1.41 1.34	0.56 0.54	0.1	0.6	0.15 0.13	0.62 0.60	0.68 0.63	0.01	0.067

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT117-1	051G05	MO-015	SC-510-28			99-12-27 03-02-13